

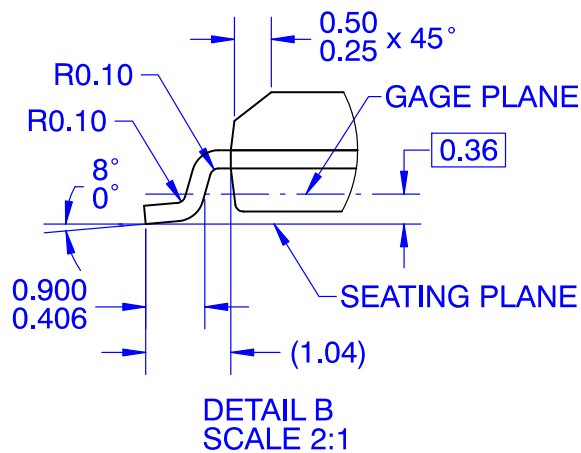
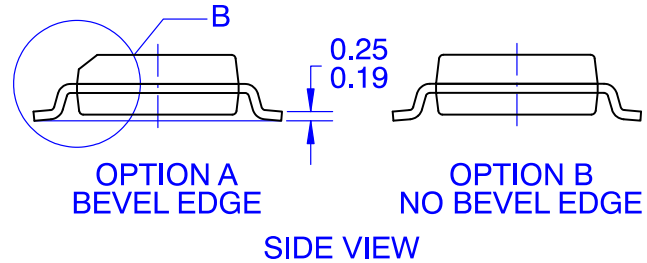
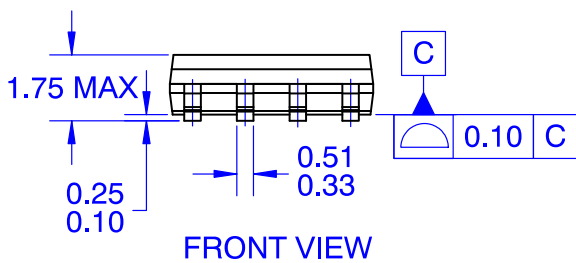
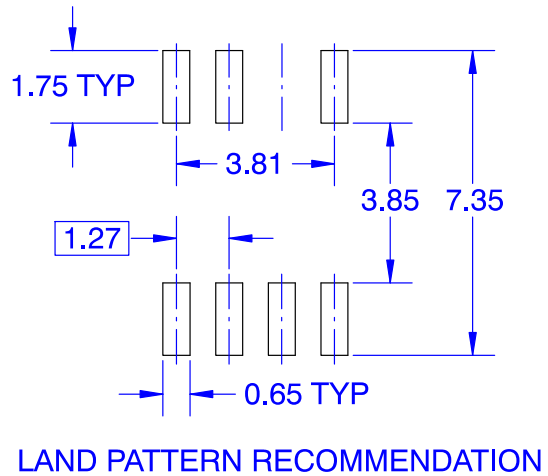
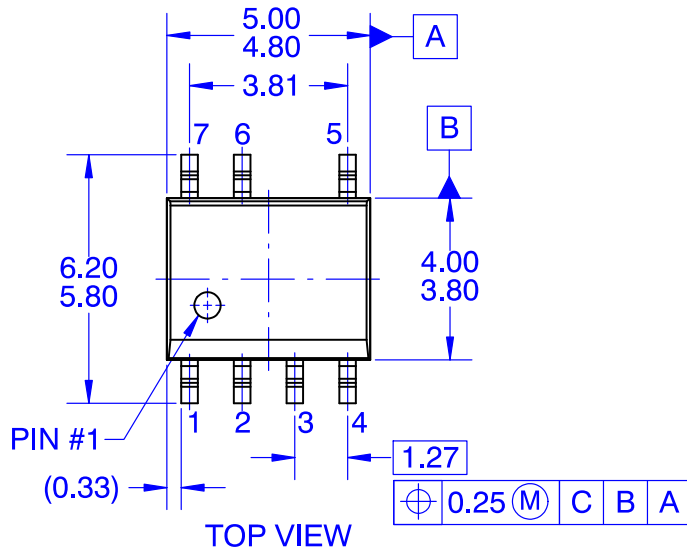
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



SOIC7
CASE 751ED
ISSUE O

DATE 30 SEP 2016



NOTES:

- A. THIS PACKAGE DOES NOT FULLY CONFORM TO JEDEC MS-012, VARIATION AA
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS

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|-------------------------|----------------------------------|--|
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| NEW STANDARD: | | |
| DESCRIPTION: | SOIC7 | PAGE 1 OF 2 |

